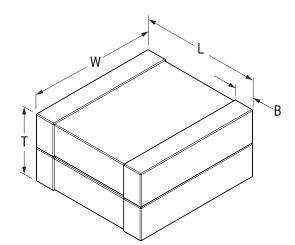


CKC33C114KDGLCTU

Aliases (CKC33C114KDGLC7800) KONNEKT KC-LINK Comm COG, Ceramic, 0.11 uF, 10%, 1,000 VDC, COG, 2-Chip Standard Orientation.



Click here for the 3D model.

Dimensions	
L	9.3mm +/-0.6mm
W	10.2mm +/-0.4mm
Т	5.1mm +/-0.4mm
В	1.27mm +/-0.4mm

Packaging Specifications	
Packaging	T&R, 180mm
Packaging Quantity	125

General Information	
Series	KONNEKT KC-LINK Comm COG
Style	KONNEKT
Description	KC-LINK with KONNEKT, SMD, MLCC, Ultra-Stable, Class I
Features	Ultra-Stable
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	2.2 g
Notes	2-Chip Standard Orientation.
Chip Size	3640-2
MSL	1

Specifications	
Capacitance	0.11 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1,200 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	9.0909 GOhms

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